

Advanced Packaging Trends for Medical Electronics

A Private Workshop hosted by Fraunhofer EMFT and TechSearch International, Inc.

November 14, 2011

- 8:30 - 9:00 Registration and coffee
- 9:00 - 9:30 **Keynote and Introduction**
Prof. Karlheinz Bock, Acting Director, Fraunhofer EMFT
- 9:30 - 10:00 **Semiconductors for Medical Applications**, Jacobo Carrasco Heres, IHS iSuppli
- 10:00 – 10:30 **Recent Developments in Active Implants**, Tim Cline, Valtronic
- 10:30 - 11:00 Break
- 11:00 – 11:30 TBD, Peter Tortorici, Medtronic (invited)
- 11:30 – 12:00 **An Embedded Die Solution, Update on the TIPS Project**, Martin McHugh, Zarlink Semiconductor
- 12:00 – 12:30 **3D-MID for Medical Applications**, Nouhad Bachnak, Cicor
- 12:30 - 1:30 Lunch
- 1:30 - 2:00 **Medical MEMS: Looking for the Next Killer App**, Jérémie Bouchaud, IHS iSuppli
- 2:00 - 2:30 **MicroSystem Technology for Medical Devices: Opportunities and Challenges Going from Macro to Micro**, Erik Jung, Fraunhofer IZM
- 2:30 – 3:00 **Reliability of Substrates for Class 3 Medical Devices**, Dr Hans-Peter Klein, Dyconex
- 3:00 – 3:15 Break
- 3:15 – 3:45 **Supply Chain Cost Modeling in Medical Electronics**, Chet Palesko, SavanSys Solutions and Larry Arne, Proteus
- 3:45 – 4:15 **Addressing Challenges for Medical Electronics Manufacturing: A Collaborative Approach**, Grace O'Malley, iNEMI
- 4:15 – 4:45 **Dealing with New RoHS Regulations in Medical Devices: An Update**, Craig Hillman, DfR Solutions
- 4:45 - 5:30 **Panel Discussion: Reliability of Medical Electronics Products: Technology at the Limit**
Moderator , Dr. Markus Riester, maris TechCon
- 5:30 RECEPTION